



NOTES:

1.MATERIAL:

1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0.
COLOR:NATURAL.

1.2 CONTACT: COPPER ALLOY.

2.FINISH:

2.1 CONTACT:

C:50~100u" NICKEL UNDERPLATING OVERALL.

CONTACT AREA: GOLD 15u" MIN

SOLDER TAIL: GOLD 1u" MIN

2:50~100u" NICKEL UNDERPLATING OVERALL.

CONTACT AREA: GOLD FLASH OVERALL

SOLDER TAIL: GOLD FLASH OVERALL

N:50u"~100u" NICKEL OVERALL

100~180u" MATT TIN OVERALL

3.REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

4.SPEC.PLS REFER TO PS-51210-XXXX-XXX

5.PART NUMBER

XXX	LOGO	DIMG	PACKING
001	ACES	3.50	/
002	ACES	1.10	51209-XXXX-06-TRP
003	ACES	2.10	/
004	ACES	2.10	51209-XXXX-XX-TRP
008	ACES	1.80	51209-XXXX-07-TRP

CKTS
PACKING
1:TUBE
3:BAG
0:TAPE REEL
4:TAPE&REEL WITH MYLAR
7:TAPE&REEL WITH COVER

PLATING

C:CONTACT AREA: GOLD 15u" MIN

SOLDER TAIL: GOLD 1u" MIN

2:GOLD FLASH OVERALL

N: MATT TIN ON CONTACT FOR LEAD FREE

CKTS	DIMA	DIMB	DIMC	DIMD	DIME	DIMF	M/S (H)
004	10.00	8.74	7.58	6.00	5.10	4.00	10.0
006	14.00	12.74	11.58	10.00	9.10	8.00	XX
007	16.00	14.74	13.58	12.00	11.10	10.00	XX
010	22.00	20.74	19.58	18.00	17.10	16.00	XX
012	26.00	24.74	23.58	22.00	21.10	20.00	XX

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY YIJIAHAO CHECKED BY BRAVE APPROVED BY BRAVE	DATE 23/05/15 DATE 23/05/15 DATE 23/05/15	 ACES ELECTRONICS TITLE 2.00mm WTB WAFER CONN. T/H S/T TYPE
	UNITS mm SCALE 5:1	 SIZE A4 SHEET NO. 1 OF 1	